

Title (en)
ELECTROFORMING PROCESS

Title (de)
ELEKTROFORMUNGSVERFAHREN

Title (fr)
PROCÉDÉ D'ÉLECTROFORMAGE

Publication
EP 4077768 A1 20221026 (EN)

Application
EP 20829037 A 20201218

Priority
• NL 2024542 A 20191220
• NL 2020050804 W 20201218

Abstract (en)
[origin: WO2021125959A1] Process of electroforming a metal structure, in particular a structure with a tip protruding from adjacent outer layers. The process comprises the following steps; - a first layer is deposited on a substrate followed by one or more next layers partially overlapping the first layer to form an intermediate structure having a substrate surface facing the substrate; - in a next step, the intermediate structure is removed from the substrate and one or more further layers are deposited on said substrate surface of the intermediate structure.

IPC 8 full level
C25D 1/00 (2006.01); **C25D 1/04** (2006.01); **C25D 5/02** (2006.01); **C25D 5/12** (2006.01)

CPC (source: EP KR US)
C25D 1/003 (2013.01 - EP KR US); **C25D 1/04** (2013.01 - EP); **C25D 1/10** (2013.01 - KR); **C25D 3/12** (2013.01 - US); **C25D 3/50** (2013.01 - US); **C25D 5/022** (2013.01 - EP US); **C25D 5/12** (2013.01 - EP US); **C25D 5/022** (2013.01 - KR); **C25D 5/12** (2013.01 - KR)

Citation (search report)
See references of WO 2021125959A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)
BA ME

Designated validation state (EPC)
KH MA MD TN

DOCDB simple family (publication)
WO 2021125959 A1 20210624; CN 114929942 A 20220819; EP 4077768 A1 20221026; JP 2023507177 A 20230221; KR 20220118447 A 20220825; NL 2024542 B1 20210902; TW 202132626 A 20210901; US 2023035647 A1 20230202

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NL 2020050804 W 20201218; CN 202080087142 A 20201218; EP 20829037 A 20201218; JP 2022537159 A 20201218; KR 20227023083 A 20201218; NL 2024542 A 20191220; TW 109143741 A 20201211; US 202017757606 A 20201218